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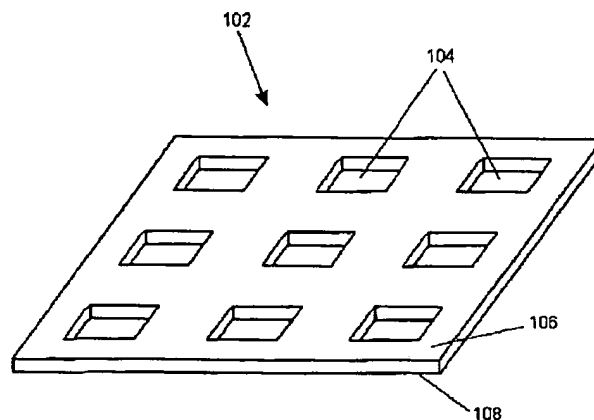
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(54) Title: **MICROELECTRONIC SUBSTRATE WITH INTEGRATED DEVICES**



(57) Abstract: A microelectronic substrate including at least one microelectronic die disposed within an opening in a microelectronic substrate core, wherein an encapsulation material is disposed within portions of the opening not occupied by the microelectronic dice, or a plurality microelectronic dice encapsulated without the microelectronic substrate core. Interconnection layers of dielectric materials and conductive traces are then fabricated on the microelectronic die, the encapsulation material, and the microelectronic substrate core (if present) to form the microelectronic substrate.

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INTERNATIONAL SEARCH REPORT

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PCT/US 01/31438

A. CLASSIFICATION OF SUBJECT MATTER
IPC 7 H01L23/538

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 5 048 179 A (SHINDO MASAHIRO ET AL) 17 September 1991 (1991-09-17) abstract; figures 1,15-18 column 1, line 35 -column 2, line 33	1-18, 21-28,31
A	column 3, line 20 -column 8, line 53 claims 5-17	19,20, 29,30
X	US 5 998 859 A (HO CHUNG WEN ET AL) 7 December 1999 (1999-12-07) abstract; figures 1,2 column 4, line 35 -column 7, line 36 claims 1-4	1-15,21

☒ Further documents are listed in the continuation of box C.

☒ Patent family members are listed in annex.

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X,P	US 6 239 482 B1 (BURDICK JR WILLIAM EDWARD ET AL) 29 May 2001 (2001-05-29) abstract; figures 1-5,12,13 column 2, line 47 -column 4, line 3	1-21
A	claim 1 -----	22-31

INTERNATIONAL SEARCH REPORT

Information on patent family members

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